PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YUNG-LUNG LIN	03/21/2018
HAU-YI HSIAO	03/21/2018
CHIH-HUI HUANG	03/21/2018
KUO-HWA TZENG	03/21/2018
CHENG-HSIEN CHOU	03/21/2018

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.	
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15922296

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 949 387 2885
Email: inbox@wpatca.com

Correspondent Name: WPAT, PC INTELLECTUAL PROPERTY ATTORNEYS

Address Line 1: 1100 QUAIL STREET, SUITE 202

Address Line 4: NEWPORT BEACH, CALIFORNIA 92660

ATTORNEY DOCKET NUMBER:	18506-1308
NAME OF SUBMITTER:	ANTHONY KING
SIGNATURE:	/Anthony King/
DATE SIGNED:	05/03/2018

Total Attachments: 2

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PATENT REEL: 045708 FRAME: 0255

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Name of Witness (optional)

Signature of Witness (optional)

ASSIGNMENT

WHEREAS, I(we), <u>LIN, YUNG-LUNG</u>, <u>HSIAO</u>, <u>HAU-YI</u>, <u>HUANG</u>, <u>CHIH-HUI</u>, <u>TZENG</u>. <u>KUO-HWA</u> and <u>CHOU</u>, <u>CHENG-HSIEN</u> whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent

United States Design Patent was	e following is checked:	
□ executed on:		
☐ filed on: 15 March 2018 Seri☐ established by PCT International Patent Application United States of America☐ issued on as U.S. Patent No		designating the
WHEREAS, TAIWAN SEMICONDUCTOR MANIaddress is NO.8, LI-HSIN RD. 6, HSINCHU Schereinafter referred to as ASSIGNEE, is desirous of acquiri	CIENCE PARK, HSINCHU	TAIWAN, R.O.C.
the United States and its territorial possessions;		
NOW, THEREFORE, for good and valuable consider ASSIGNOR, by these presents do sell, assign and transfer and to said INVENTION and application throughout the Patent granted on any division, continuation, continuation terms for which the same may be granted, including all presents of the same may be granted.	unto said ASSIGNEE, the entire rig United States of America, including in-in-part and reissue of said applica	tht, title, and interest in ing any and all Letters ition for the full term or
ASSIGNOR further covenants that no assignments, so or entered into which would conflict with this Assignment	ale, agreement or encumbrance ha	s been or will be made
ALSO, ASSIGNOR hereby agrees to execute any docur filing, prosecution and maintenance of said application of said INVENTION, including additional documents that massaid INVENTION, all without further consideration. ASSIGNEE'S expense, to identify and communicate to ASSIGNEE'S expense, to identify and communicate to ASSIGNOETHIN TO that are within ASSIGNOR'S potestimony on behalf of ASSIGNEE that lawfully may be maintenance, litigation and defense of any patent applicant materials. ASSIGNOR'S obligations under this instrument. ASSIGNOR'S obligations under this instrument.	or any other patent application(s) in the required to affirm the rights SIGNOR also agrees, without furth SIGNEE at ASSIGNEE'S request documents of the provide required of ASSIGNOR in respectation or patent encompassed we	on the United States for of ASSIGNEE in and to er consideration and auments and information further assurances and ect of the prosecution ithin the terms of this
ALSO, ASSIGNOR hereby authorizes and requests the and all Letters Patent referred to above to ASSIGNEE, as the same, for ASSIGNEE's sole use and behoof; and for the successors, to the full end of the term for which such Lesame would have been held by ASSIGNOR had this assignment.	he ASSIGNEE of the entire right, tit e use and behoof of ASSIGNEE'S le etters Patent may be granted, as f	le and interest in and to
Assignor Name LIN, YUNG-LUNG	Address NO.8, LI-HSIN RD. 6, HS PARK, HSINCHU, TAIWAN	INCHU SCIENCE (R.O.C.)
Signature of Assignor	Date of Signature	

-1-

Name of Witness (optional)

Signature of Witness (Optional)

Assignor Name HSIAO, HAU-YI	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN (R.O.C.)
Signature of Assignor (X) HSIAO, HAU—YI	Date of Signature (X) >0 (8 3 >1
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name HUANG, CHIH-HUI	Address NO.43, ALY. 30, LN. 165, YONG-AN RD., YONGKANG CITY, TAINAN COUNTY 710, TAIWAN (R.O.C.)
Signature of Assignor (X) HUANG CHIH-HUI	Date of Signature (X) >>/8, 3 >/
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name TZENG, KUO-HWA TZUNZ KUO -HWA	Address 4F4, NO.300, SEC. 3, HEPING W. RD., WANHUA DISTRICT, TAIPEI CITY 108, TAIWAN (R.O.C.)
Signature of Issignor (X) Zeng Kuo - Hwa	Date of Signature (X) 20 (8, 3, 2)
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name CHOU, CHENG-HSIEN CHOU, CHENG-HSIEN	NO.24-2, LANE 25, XINJIAN RD., SOUTH DIST., TAINAN CITY, TAIWAN (R.O.C.)
Signature of Assignor (X) CHOU CHENG - HSIEN	Date of Signature (X) つい(f らう. フー
Name of Witness (optional) Signature of Witness (optional)	Name of Witness (optional)
Signature of Witness (uptional)	Signature of Witness (Optional)